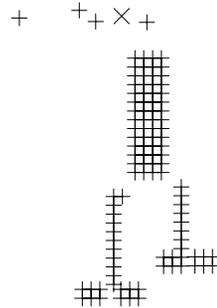


NOTES

MATERIAL: FR4 1 OZ COPPER EACH LAYER.
ALL HOLES PLATED THRU WITH 1 OZ COPPER MIN.
FINAL COPPER ON EXTERNAL LAYERS = 2 OZ. MINIMUM.

For best thermal performance,
Make GND copper as large as
possible, except on layer 1
directly under U1.



All footprints and spacings have been set
according to common PCB fabrication
and assembly practices. If necessary,
these spacings can be modified according to
customer manufacturing capabilities.

EN63A0QI Critical Component Circuit

This layout shows the critical components
and traces for minimum footprint with ENABLE
tied to Vin and pre-biased startup enabled.
Alternate ENABLE and pre-bias configurations, & other
low-power pins need to be connected and routed
according to the customer application.

Solder mask and paste layer openings should be
reviewed and optimized to meet customer
PCB fabrication and assembly guidelines.

SIZE	QTY	SYM	PLATED	TOL
8	104	+	YES	NOTE
16	1	X	YES	STD

NOTE: USE 13 MIL DRILL FOR 8 MIL PLTD HOLES
PLUGGING/FILLING OF THESE HOLES IS ACCEPTABLE.